

# III-V nanowires for energy: low power nanoelectronics and other opportunities.

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# Energy crisis in ICT



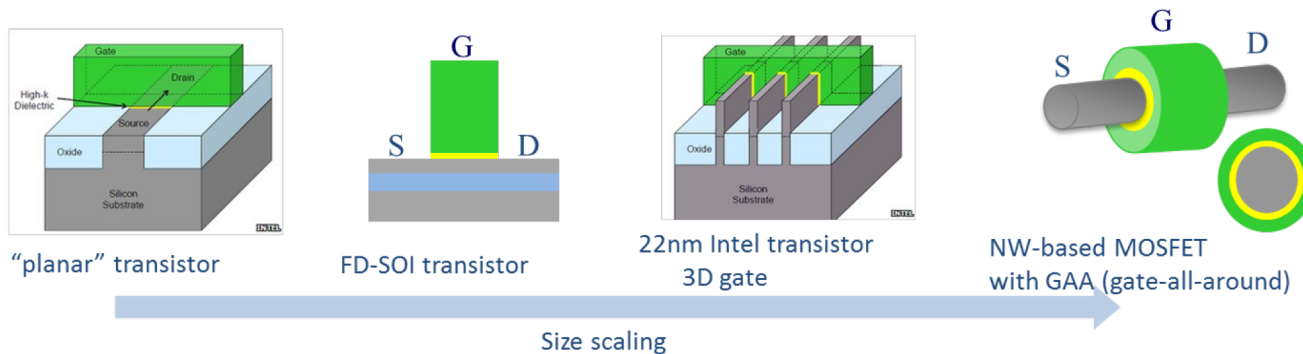
Data Center farm

- > 3% of the world's electricity supply
- > 2 % of total greenhouse gas emissions

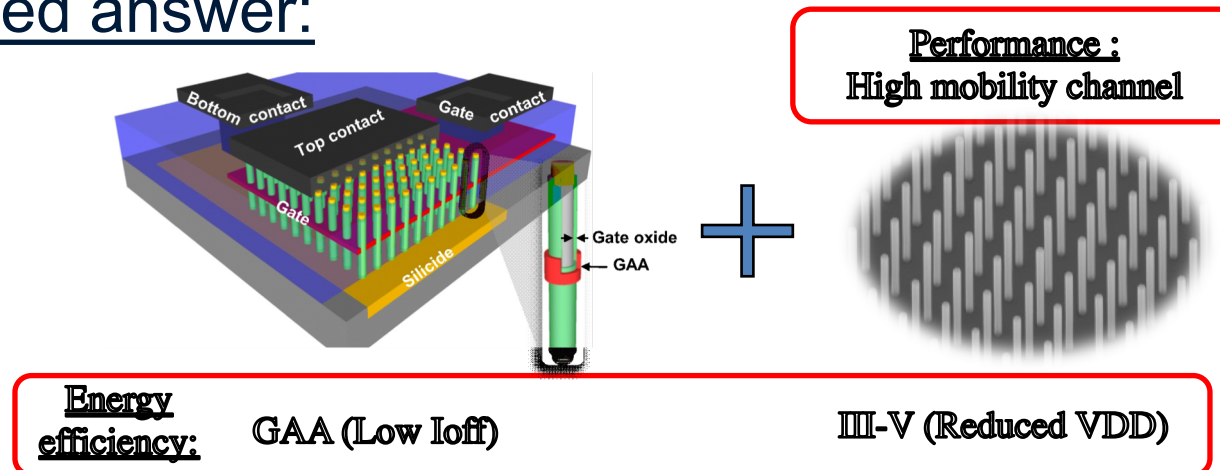
- > Reducing the power consumption in MOS device is the key since most of the operating power for servers and storage is consumed by microprocessors and memories.

# Scaling of MOS device: power issue

- > Motivation: pursue transistor miniaturization to the extreme scaling.
- > Enhanced electrostatic control -> new 3D architecture.

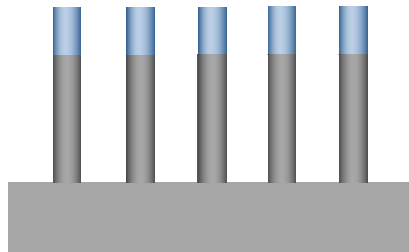


## > Proposed answer:

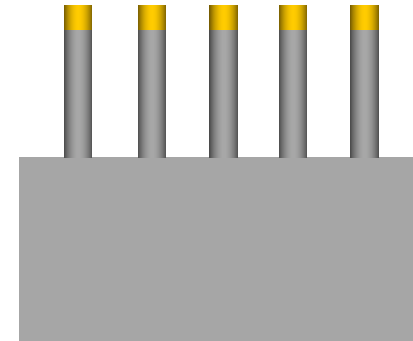


# Realization of III/V NW arrays

Top  
↓  
Down



Up  
↑  
Bottom

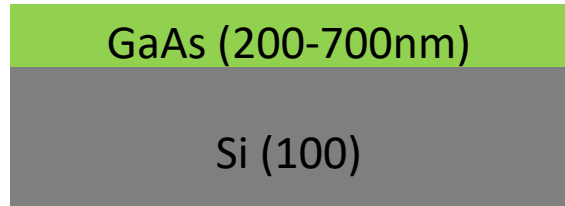


Issues associated to nanoelectronic applications:

- > Localization/density/diameter
- > Quick integration in standard process flow, CMOS compatible
- > Si platform integration (high lattice mismatched).

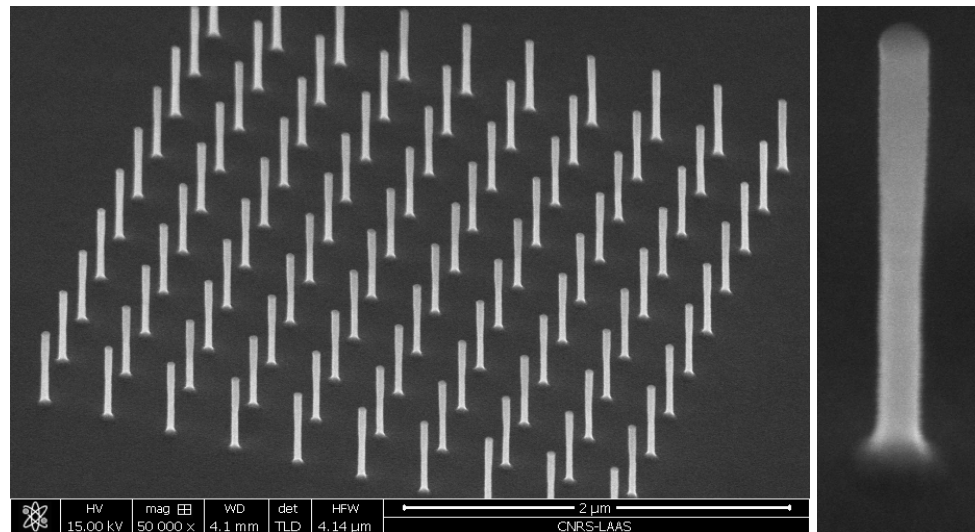
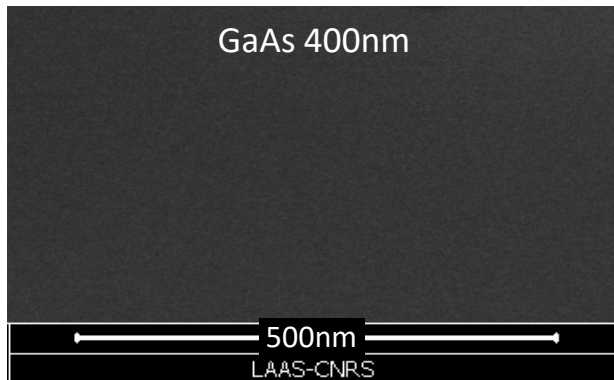
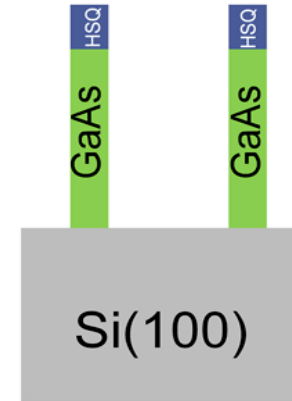
# T-D: III-V NWs on Si

III-V layer grown on Si(100)



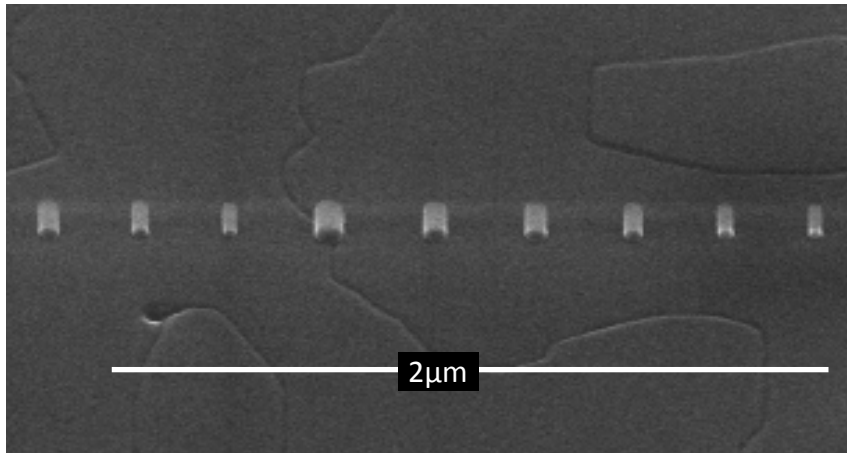
MOCVD 300mm  
(CEA-LTM Grenoble  
T. Baron *et al.*)

Patterning  
+ RIE →

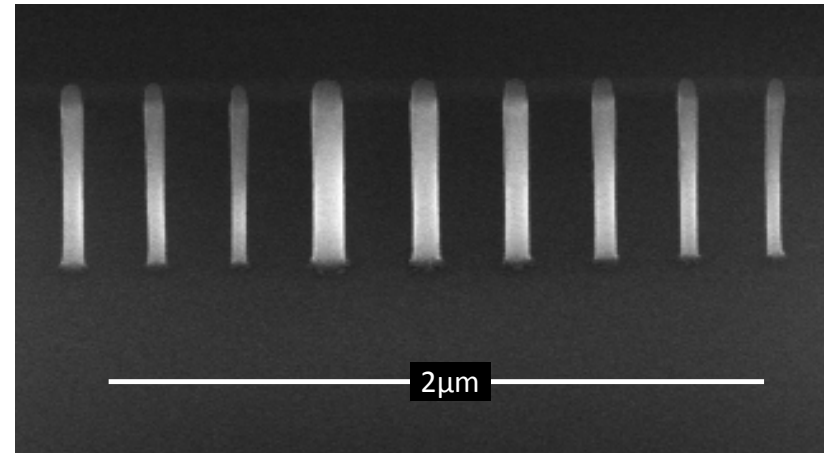


# Hetero structured III-V / Si NWs by T-D

EBL: Resist nanodots

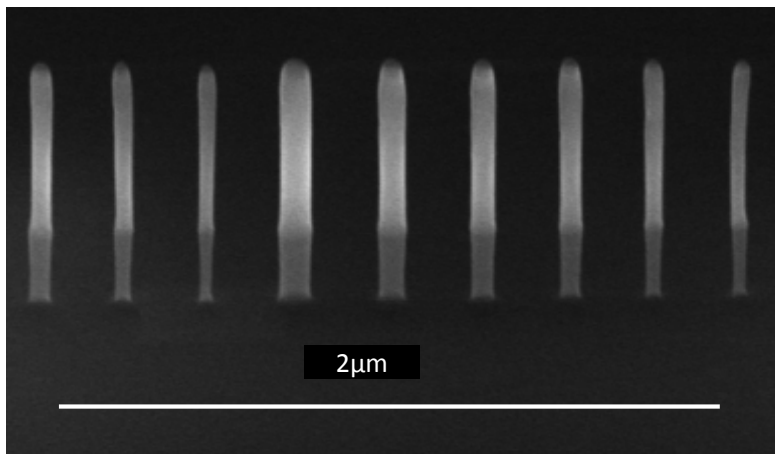


Chlorine plasma etching: GaAs nanowires



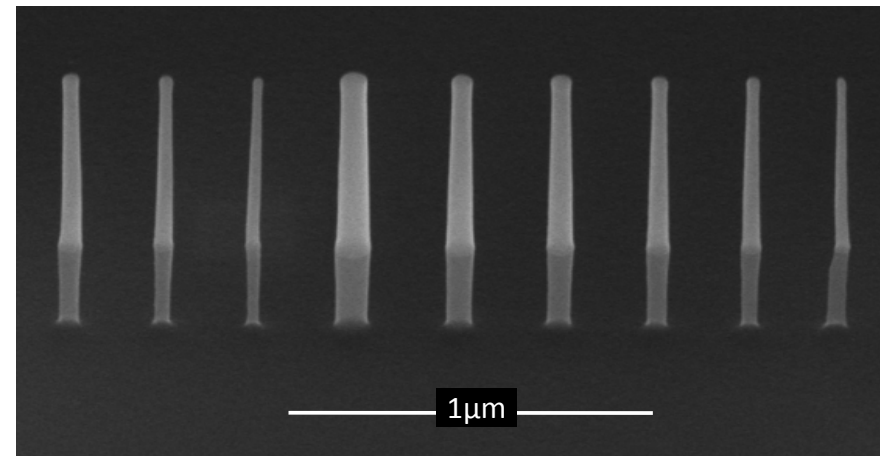
Fluorine plasma etching

GaAs-Si heterostructured NWs with resist



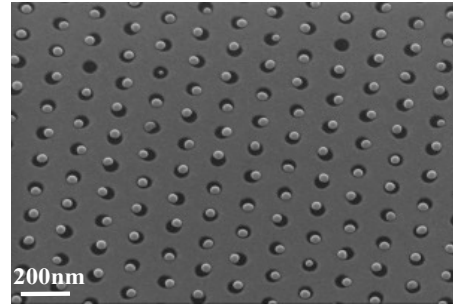
HF + Plasma O<sub>2</sub>

GaAs-Si hetero structured nanowires

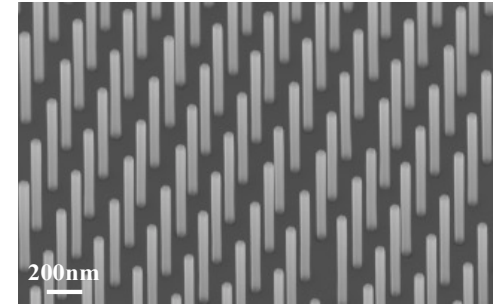


# B-U: Positioning and Yield of NW arrays

- > Direct integration of high mobility materials on silicon by surface nanostructuring



T-D: Nano-hole structuration in thermal SiO<sub>2</sub> layer.

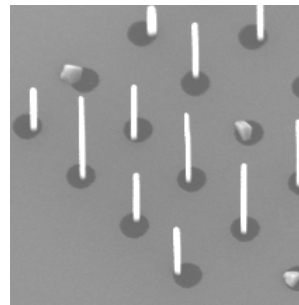


B-U growth: VLS growth of GaAs NW by MBE

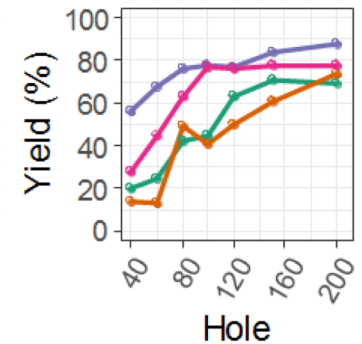
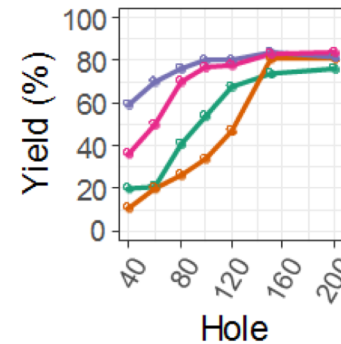
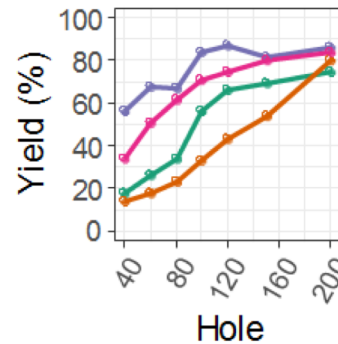
- > High yield of NW arrays on Si

- > Key parameters:

- Hole diameter
- In and As fluxes
- Temperature



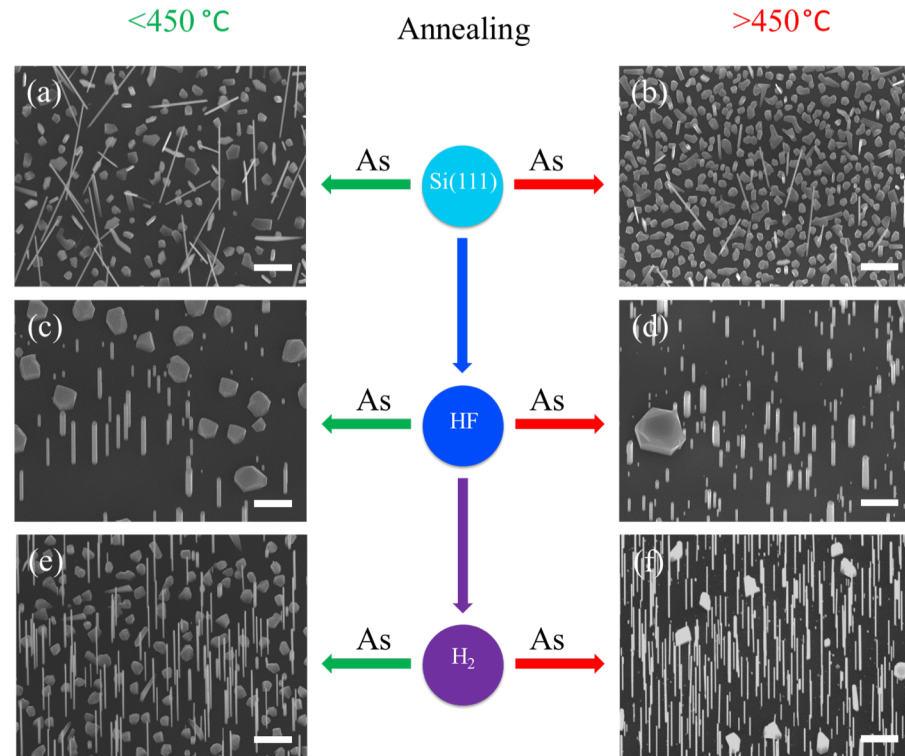
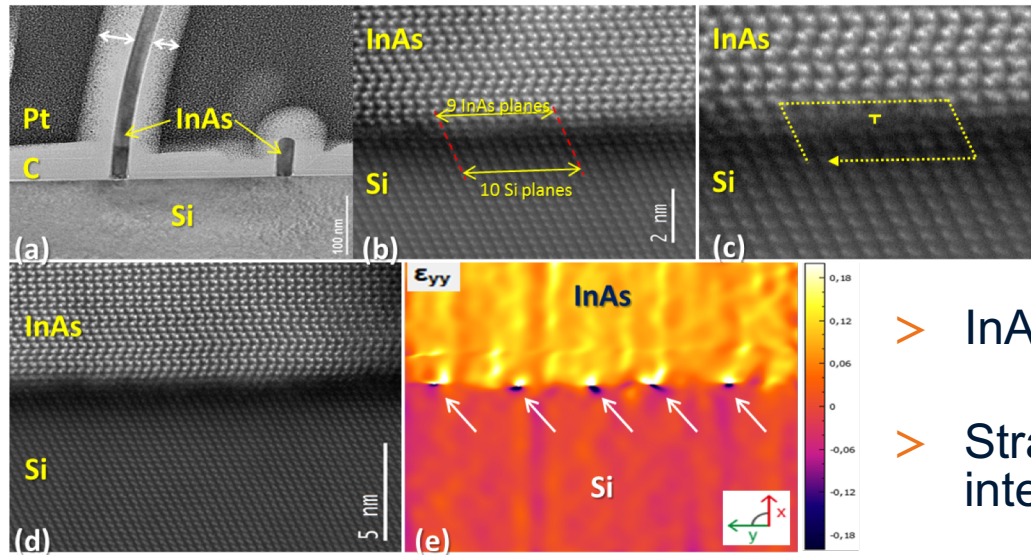
InAsSb



# B-U: a CMOS compatible integration

- > We developed a CMOS compatible process for the integration of high-mobility InAs nanowires on Silicon

In-situ annealing with As  
+  
HF 5%  
+  
H<sub>2</sub> plasma



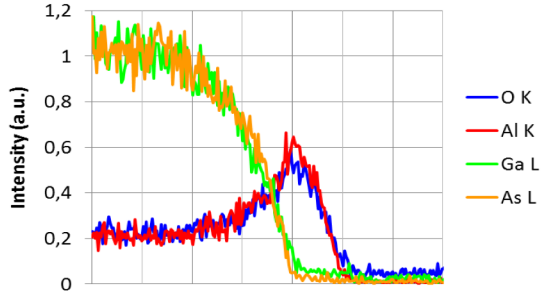
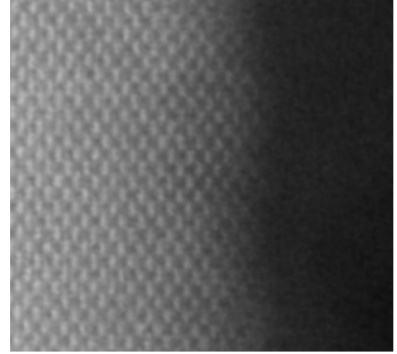
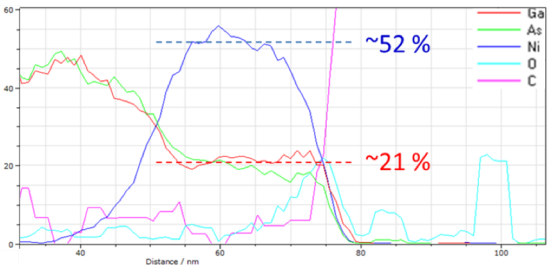
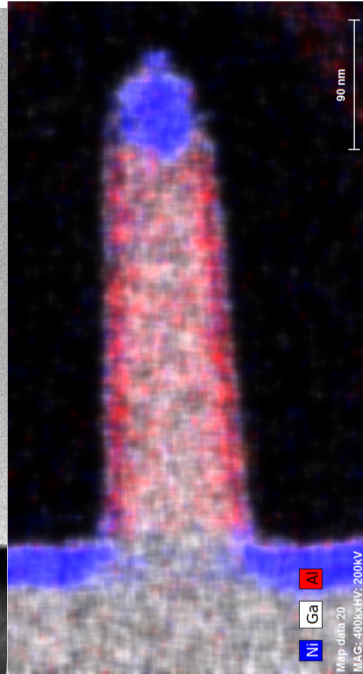
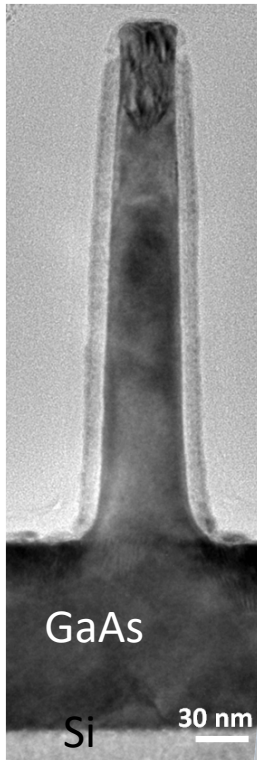
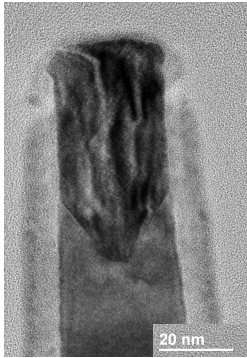
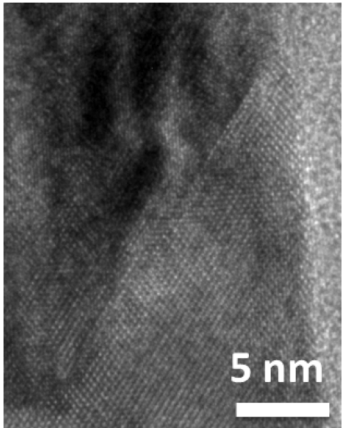
- > InAs nanowires are epitaxially grown on Si(111)
- > Strain and dislocations are locked at the InAs-Si interface



> 2 main roadblocks in III/V MOSFETs

- Low resistive S/D contacts (CMOS comp)

- Gate oxide integration (low defects)



**Low Resistive contacts on 3D NWs:**

- Ni<sub>2</sub>GaAs alloy (RTA anneal)
- CMOS-compatible technology
- Contact resistivity :  $2 \cdot 10^{-4} \Omega \cdot \text{cm}^{-2}$

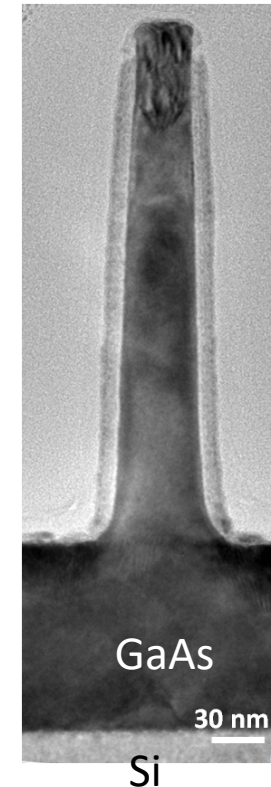
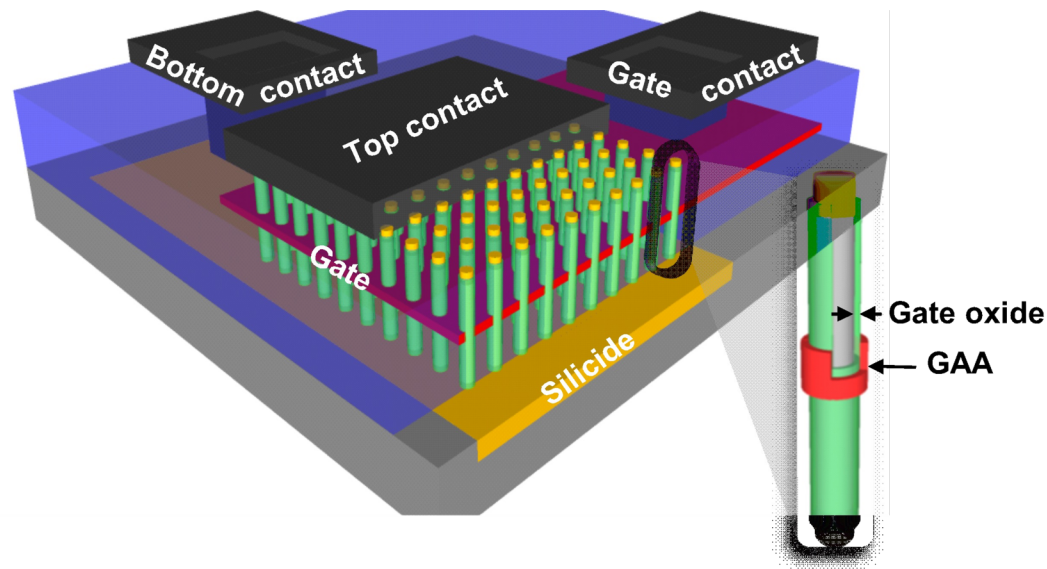
**High-k gate oxide:**

- Conformal Al<sub>2</sub>O<sub>3</sub> layer by ALD
- Surface preparation : sulfur passivation + in-situ cleaning
- Interface defect density:  $5 \cdot 10^{12} \text{ cm}^{-2} \cdot \text{eV}^{-1}$
- Oxide trapped charge :  $2 \cdot 10^{12} \cdot \text{cm}^{-2}$

# Toward the full device demonstration

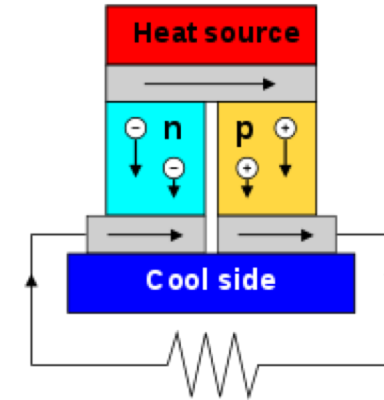
## > Low power demo targeted:

- VDD ~ 0.5V
- Physical gate length < 15nm



## > What is thermoelectricity ?

- A direct conversion of temperature gradients into electricity (Seebeck effect)



## > Why is it interesting ?

- Everywhere energy is used a part is “lost” in heat (computers, cars, industry ...)

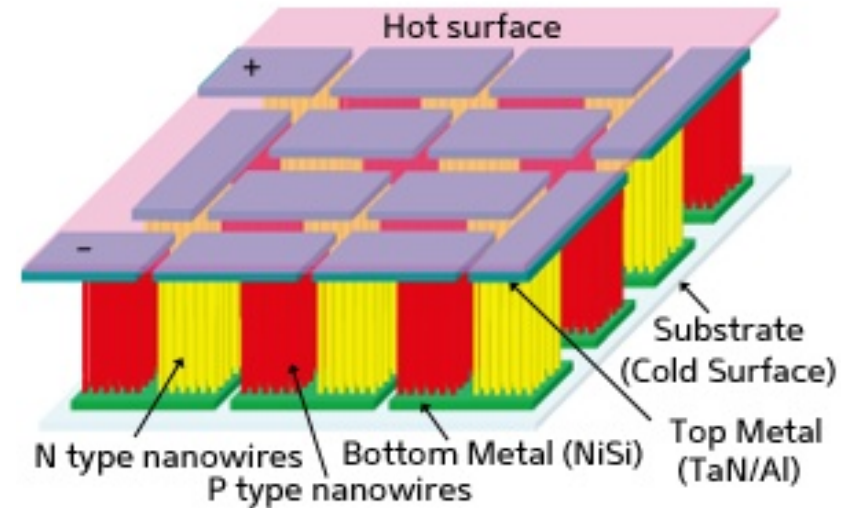
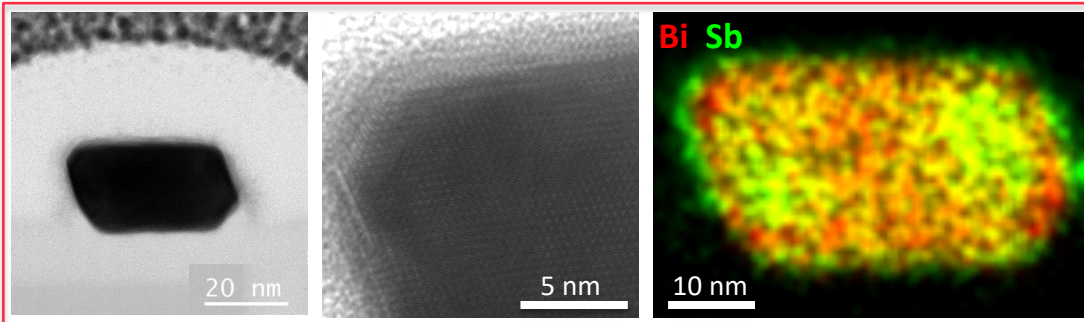
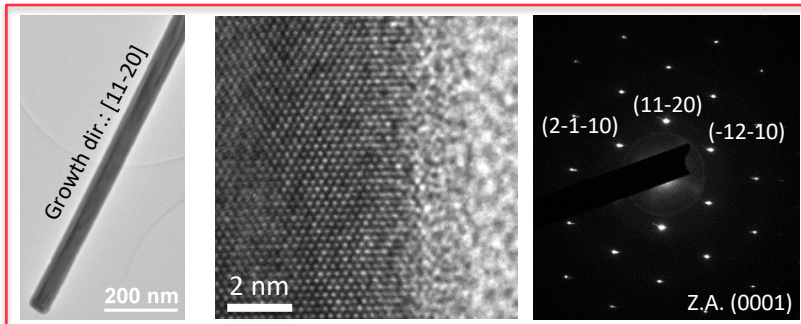
⇒ The idea is to “collect” these losses

## > Nano-generators ?

- Better performances than bulk (improved ZT) due to a lower thermal conductivity in NWs
- Interesting for “local” production

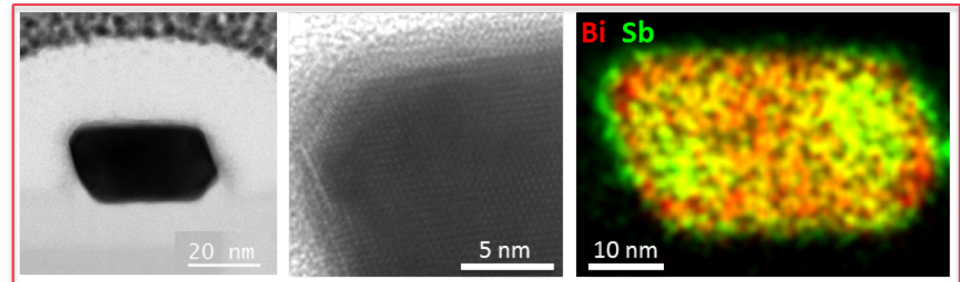
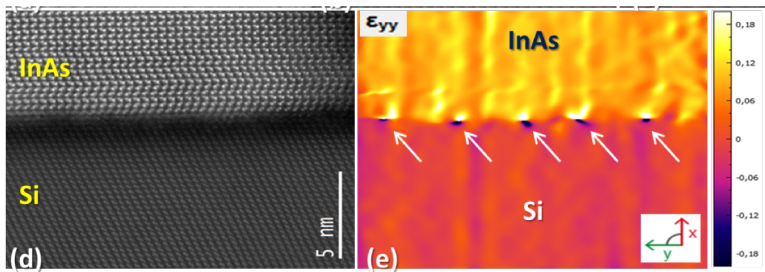
- > Using material engineering integrated on Si ...

BiSb NWs



- > ... and developing new nanoscale Topological Insulators (near zero electrical resistance + high thermal resistance = high ZT) for improved thermoelectric devices

- > III-V nanowires devices for energy:
  - low power nanoelectronics : vertical III/V nanowires FETs: from NWs patterning to integration issues.
  - Other opportunities: Thermoelectric ...



**People involved in this thematic at LAAS:**

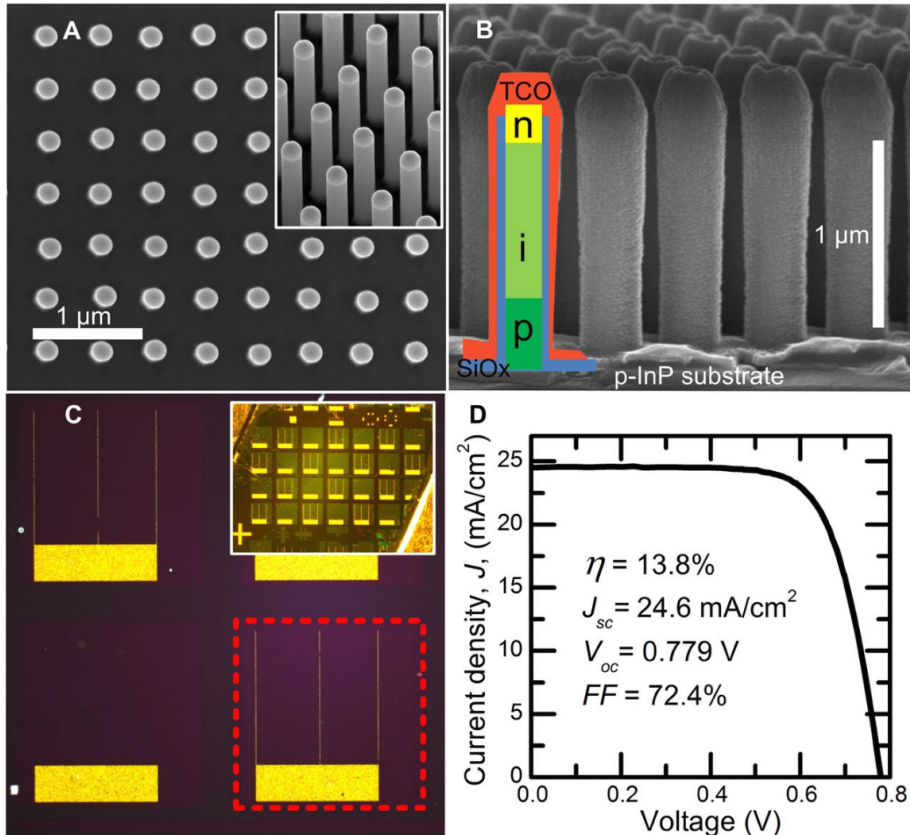
**Nicolas Mallet, Daya Dhungana, Aurélie Lecestre, Fuccio Cristiano,  
Pier Francesco Fazzini, Emmanuel Scheid, Julien Pezard, Sébastien  
Plissard, Guilhem Larrieu**



# Other Opportunities : Solar cells

## InP Nanowire Array Solar Cells Achieving 13.8% Efficiency by Exceeding the Ray Optics Limit

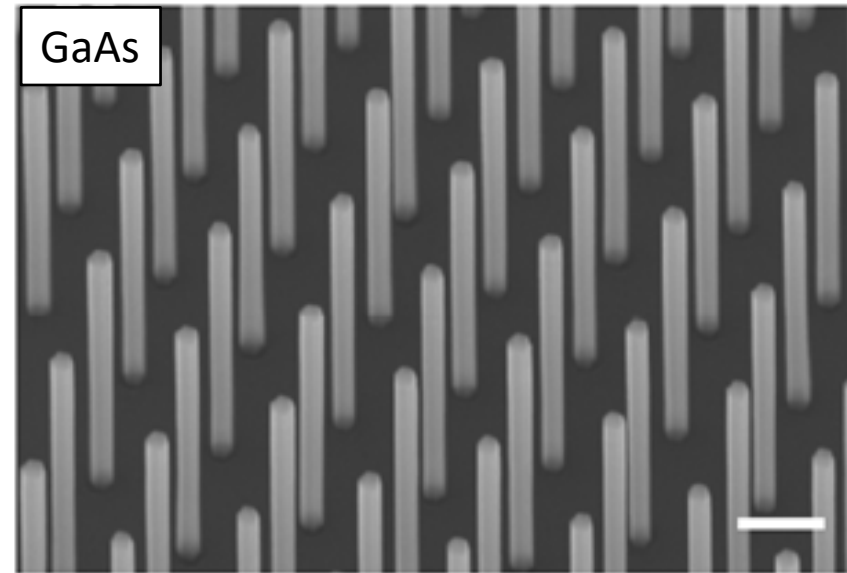
Jesper Wallentin,<sup>1</sup> Nicklas Anttu,<sup>1</sup> Damir Asoli,<sup>2</sup> Maria Huffman,<sup>2</sup> Ingvar Åberg,<sup>2</sup>  
Martin H. Magnusson,<sup>2</sup> Gerald Siefer,<sup>3</sup> Peter Fuss-Kailuweit,<sup>3</sup> Frank Dimroth,<sup>3</sup>  
Bernd Witzigmann,<sup>4</sup> H. Q. Xu,<sup>1,5</sup> Lars Samuelson,<sup>1</sup> Knut Deppert,<sup>1</sup> Magnus T.  
Borgström<sup>1\*</sup>



Scienceexpress/ <http://www.sciencemag.org/content/early/2013/01/17/10.1126/science.1230969>

State of the art for NW solar cells

> Using III-V nanowires integrated on Si to build tandem solar cells



Using processes developed in LAAS for direct integration on silicon